IN THE SPECIFICATION

Please replace the paragraph beginning at page 3, line 28, with:

The separator plate according to the invention, thus, comprises a core layer or central layer made of a strongly heat-conductive metal such as aluminum or copper, and this core layer is connected at least on one side, preferably on both sides, with a hard metal such as, for instance, fine steel, carbon steel, and even nickel or the like, by cold-plating (roll-bonding). Such a hard-metal ~~plating~~ cladding can be comparatively thin, for instance, in the order of about 0.075 mm, whereas the core made, for instance, of aluminum or copper, has a thickness of 0.35 mm. Roll-bonding or ~~cold-plating~~ cold-cladding causes the planar connection of metals in the manner of a fusion while bringing about the advantageous effect that, during heating, the thermal expansion can occur only to an extent corresponding to that of the hard-metal plating, which means that the relatively strong thermal expansions of heat-conducting metals like aluminum or copper, if used alone for the separator plate, will no longer occur. Add to this that the thermal expansion, for instance of steel, which is inherently substantially lower than that of aluminum, will take effect only at a comparatively high temperature, yet such a high temperature will not occur at the pressing of individual layers presently proposed for the production of printed circuit board components. For instance, aluminum separator plates having a size of 600x450 mm would undergo an expansion of about 5 mm in any direction, whereas a separator plate of steel having identical dimensions would experience an expansion as such of

about 2 mm - yet only at high temperatures, and of only 0.1 mm to 0.2 mm, however, during pressing at the temperature in question of 180°C or 200°C. By fusing with the hard plating material, the core layer made of a heat-conductive metal is forced to adapt to such low expansion.